

Development of the ATLAS ITk BCM' system for beam abort and luminosity determination at the HL-LHC based on polycrystalline CVD diamond

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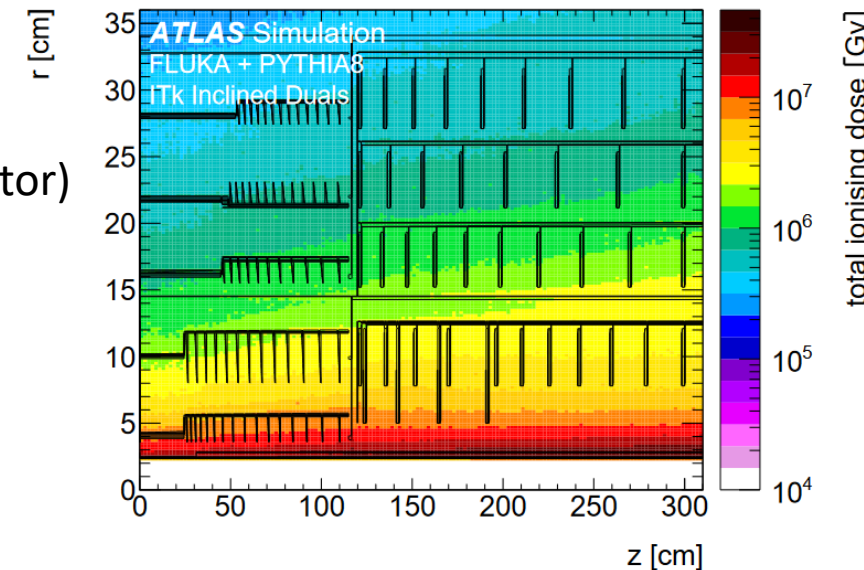
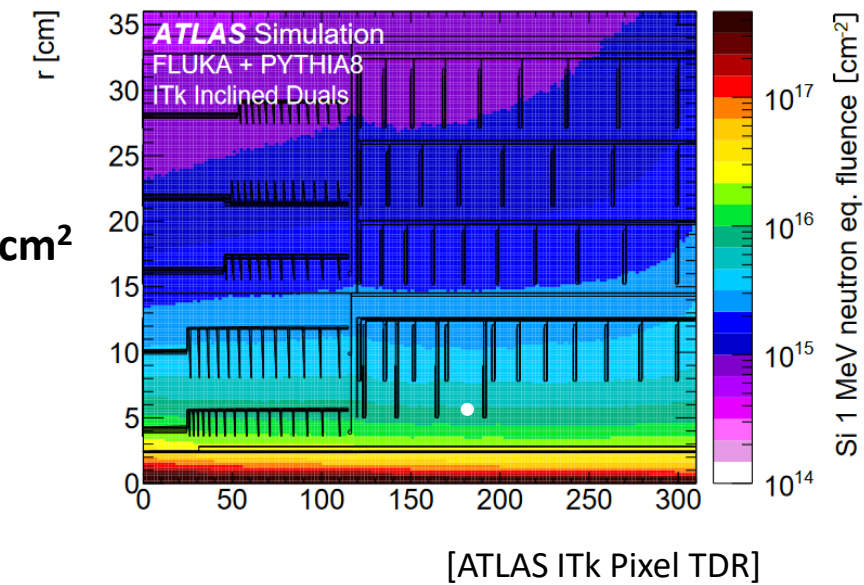
on behalf of ATLAS ITk BCM' group

- ATLAS BCM and BCM' Upgrade
- Sensor and front end
- Measurements
- Module and services
- Summary

- Beam Conditions Monitor (BCM) in ATLAS at the LHC:
 - Based on radiation tolerant diamond sensors
 - Installed since 2008
 - Located in the Pixel Detector at $z = \pm 184$ cm, $r = 5.5$ cm
 - **NIEL 1×10^{15} n_{eq}/cm², TID 50 Mrad**, charged particle flux up to **60 MHz/cm²**
- BCM provides bunch-by-bunch detection for **Beam Protection and Luminosity measurement**:
 - Per-bunch fast safety system (*abort*)
 - Background monitoring
 - Per-bunch luminosity meter (*lumi*)

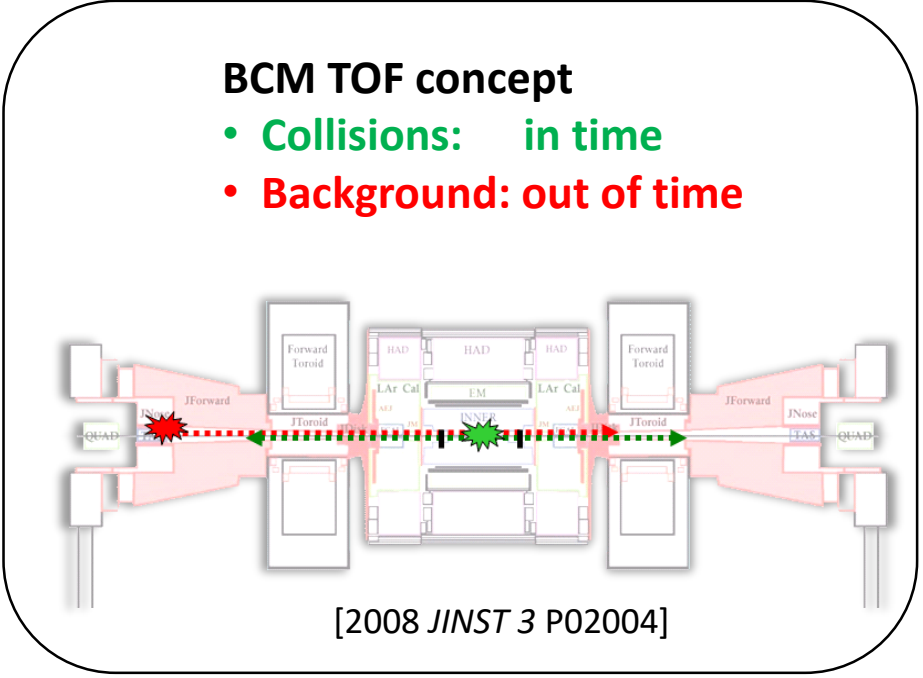
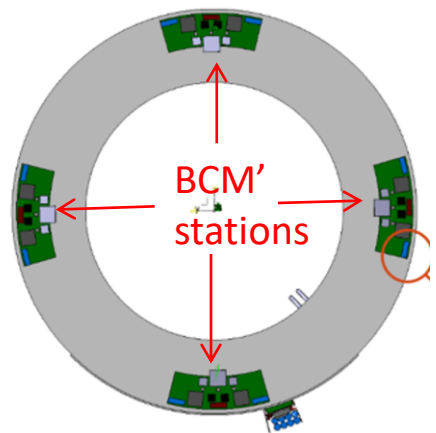
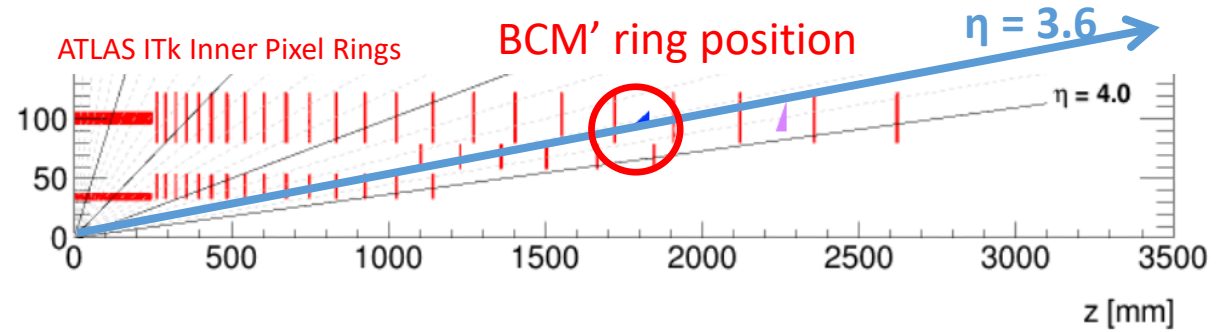
} Can abort LHC beam to protect the tracking detector
- HL-LHC: particle density will increase by almost an order of magnitude
 - Charged particle flux up to **230 MHz/cm²** at pile up $\mu = 200$
 - **NIEL 3×10^{15} n_{eq}/cm², TID 300 Mrad** after **2000 fb⁻¹** (including x 1.5 safety factor)

A new **BCM'** system will be installed in ATLAS ITk in 2024
 BCM' group: OSU, JSI, Manchester, Wiener Neustadt, CERN

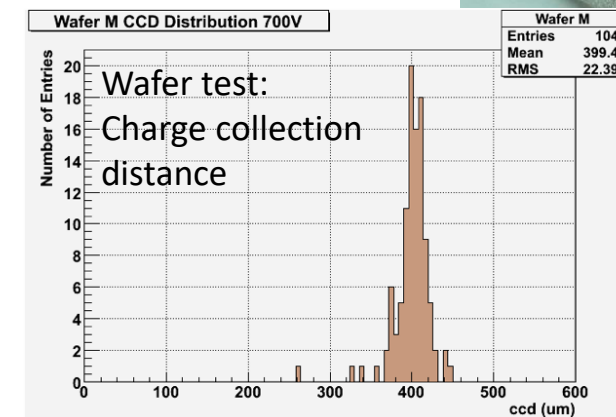
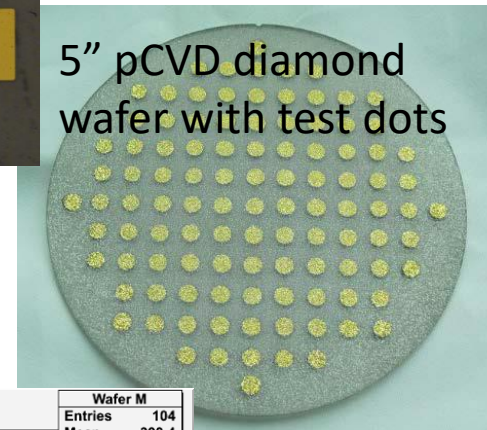
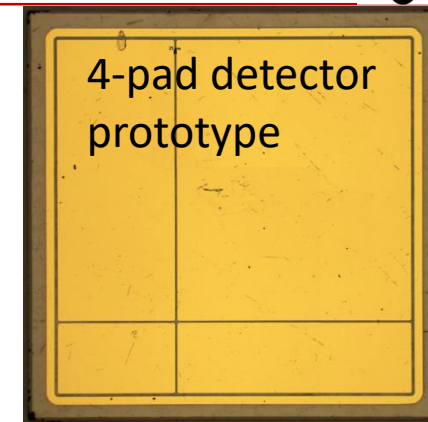
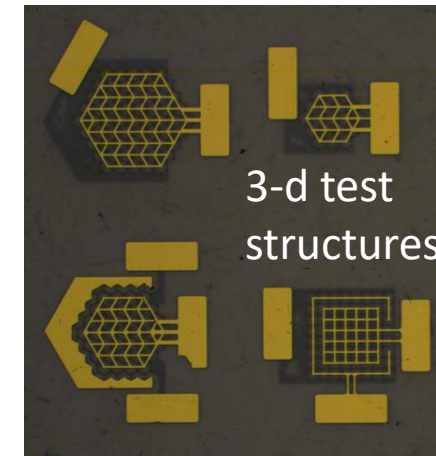


- Located within the new ATLAS ITk Pixel Inner system on both detector sides at $r = 100$ mm, $z = \pm 1800$ mm (6.25 ns) from Interaction Point
- Collision/background separation based on Time of Flight
 - **Luminosity:** **Collision products** arrive simultaneously on both detector sides (in-time)
 - **Beam protection:** **Background** arrives out-of-time, 12.5 ns interval between two sides
- Four stations per each side of the detector
- Multiple detectors by function
 - Abort (dynamic range 10^5 MIP)
 - Beam Loss Monitor (BLM) – slow, integrating, electronics copied from LHC machine
 - Luminosity (single MIP sensitivity)

Each with own sensor



- Sensitivity on very broad range of particle fluxes required
 - Four orders of magnitude, $\mu_{\text{vdM}} = 0.01 \rightarrow \mu_{\text{ultimate}} = 200$
 - Dynamic range flexibility by **segmenting the sensor** into pads of varying size
- Three types of **polycrystalline chemical vapor deposition (pCVD) diamond** sensors and one **silicon** sensor per station:
 - **5 mm x 5 mm** (abort), four pads
 - **10 mm x 10 mm** (lumi), three pads (size $1 \text{ mm}^2 - 50 \text{ mm}^2$)
 - **1 mm x 1 mm 3D** (lumi), single pad, hex or square electrode cells ($53 \mu\text{m}$ sense-to-field electrode spacing), $C = 5 \text{ pF}$, highest radiation tolerance
 - Small **Si pad/strip** (lumi), 10 mm^2 , 5 pF
- Diamond sensors produced by US vendor II-VI (worked with RD42)
 - Three $500 \mu\text{m}$ thick 5-inch wafers have been grown for the project
 - Prototypes delivered Dec 2021
 - Promising first measurements of charge collection, long term current stability
- Preproduction will start in mid-2022



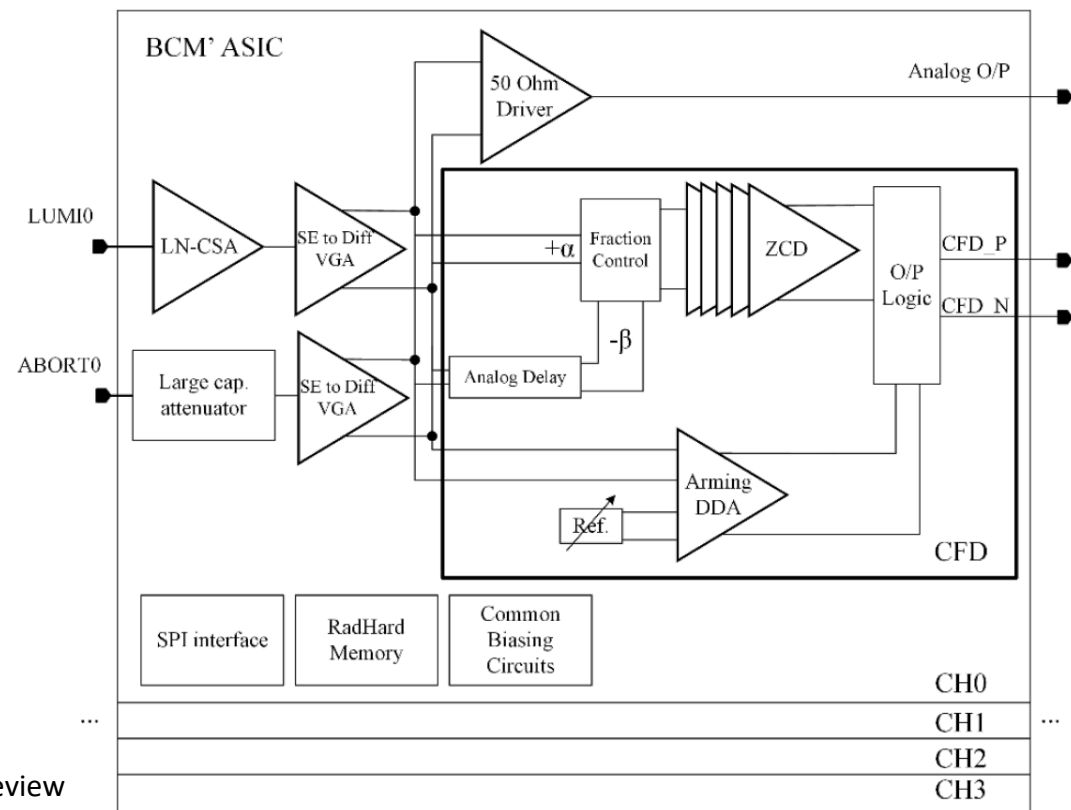
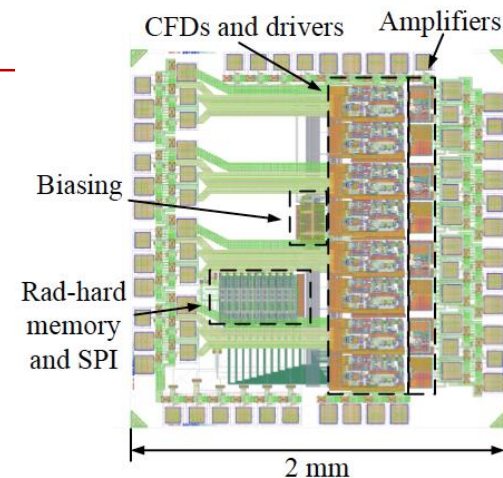
- Calypso: New custom 4-channel front end ASIC
 - TSMC 65 nm process, Multi Project Wafer (MPW), size 2 mm x 2 mm
 - Two (mutually exclusive) input options per channel: *lumi/abort*

CALYPSO specifications:

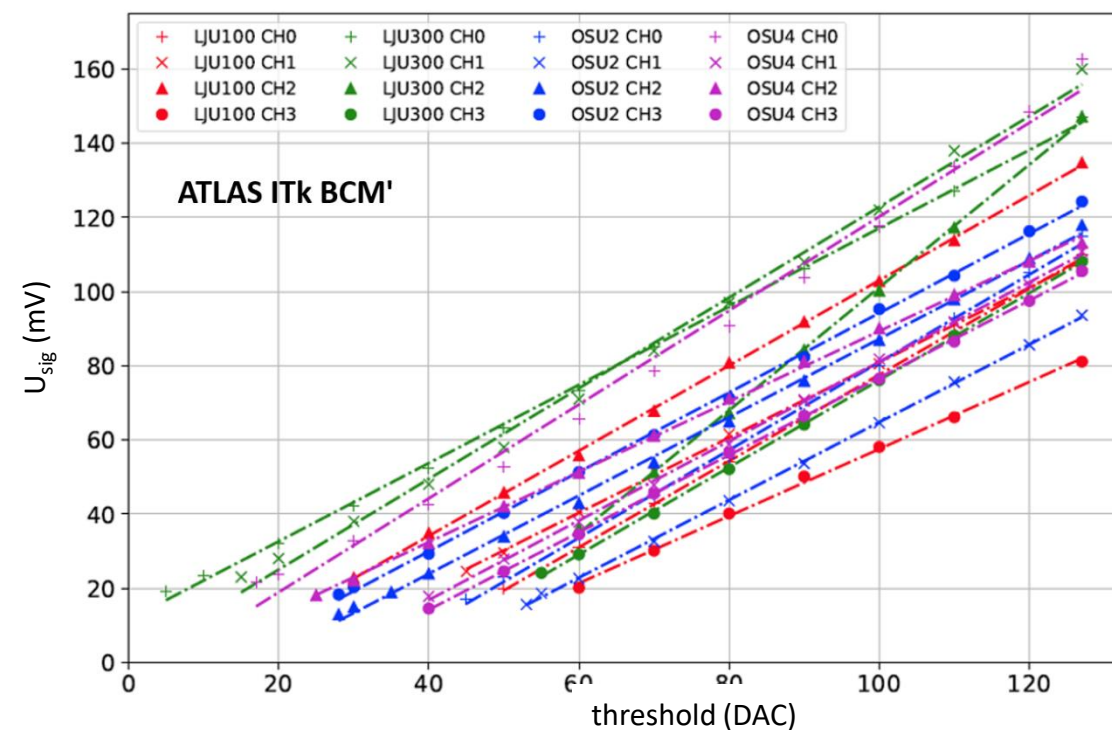
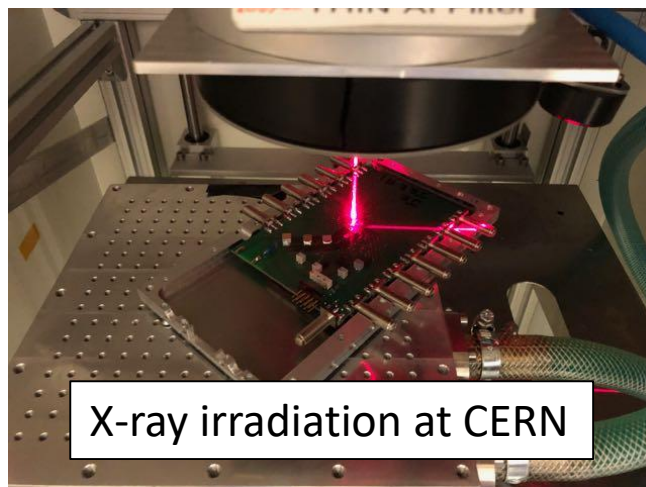
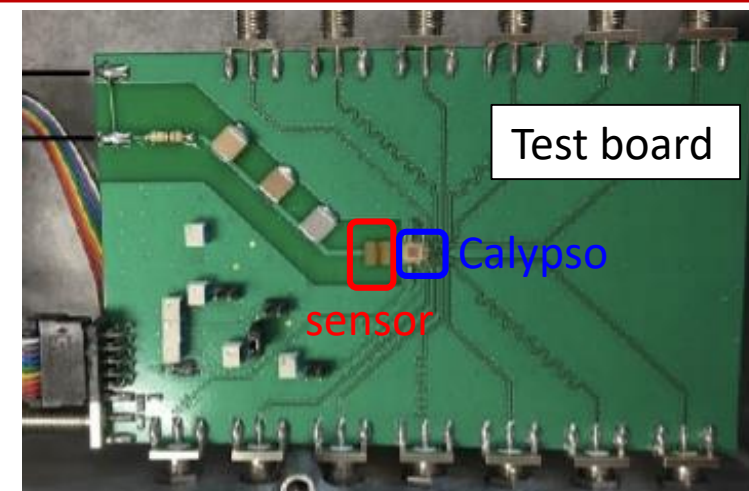
- Optimized for C_{det} **2–5 pF**
- $t_{peak} < 1.5$ ns, $t_{settling} < 15$ ns (at $C_{det} = 2$ pF)
- $\sigma_{jitter} < 100$ ps (at $C_{det} = 2$ pF for > 3.6 ke⁻ signals in simulation)
- **lumi**: ± 50 ke⁻ dynamic range, $(110 + 55/pF)$ e⁻ noise gain 55 mV/fC
- **abort**: ± 750 Me⁻ dynamic range, 830 ke⁻ noise, gain 8.2 μ V/fC
- **digital LVDS output**, analog preamp output for testing

- 3rd iteration Calypso_C received Dec 2020
- 4th planned for June 2022
- ASIC FDR early 2022, PRR early 2023

FDR ... Final Design Review
 PRR ... Production Readiness Review



- Single chip test boards assembled at OSU and JSI
- Basic functionality test ok
 - Except (much) larger threshold offset spread than expected from simulation
 - Consistent results at OSU and JSI
- Chips irradiated up to 300 Mrad X-ray (unpowered)
 - Functional after 300 Mrad
 - < 20 % of variation on analog parameters observed
 - Need to irradiate powered and cold (counter-effects!)
- I²C for chip configuration fully tested



Single Event Effects test at PSI with Calypso_C

- Aug and Oct 2021, PIF at PSI, 230 MeV protons (3.5e13 p/cm² total)
 - **Unirradiated** Calypso_C and Calypso_C irradiated with **300 Mrad** (X-ray)
- Test procedure:
 - Triple Modular Redundancy (TMR) register cells with active feedback
 - 30 8-bit registers i.e. 240 bits loaded with a binary pattern, read out every 10 s
 - If change observed reload and re-start reading

Results:

- No events observed with unirradiated chip
 - Rate consistent with ITk strips upper limit 1e-14 cm²
- Two events observed in chip irradiated to 300 Mrad

1111 1111 → 1111 1101
0010 1100 → 0100 1100

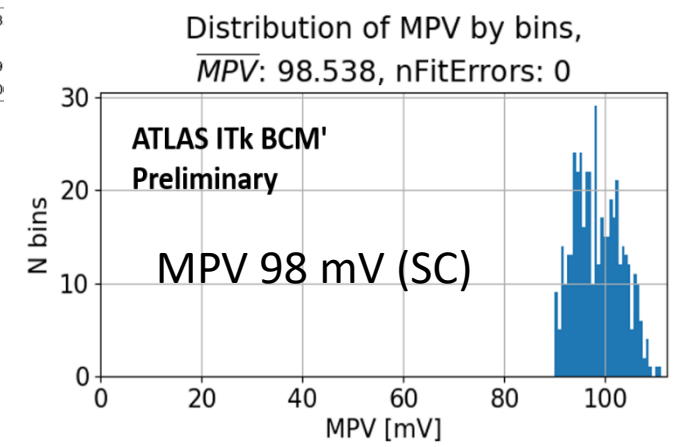
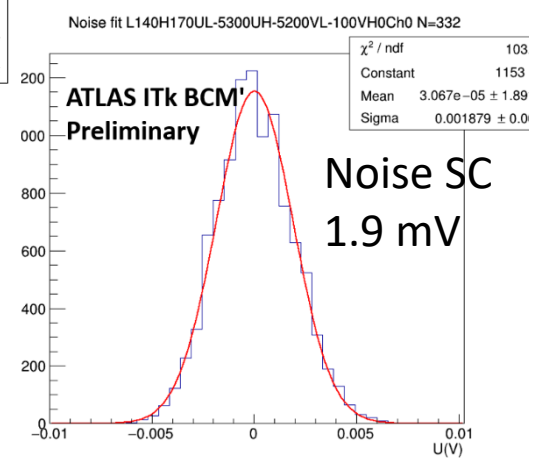
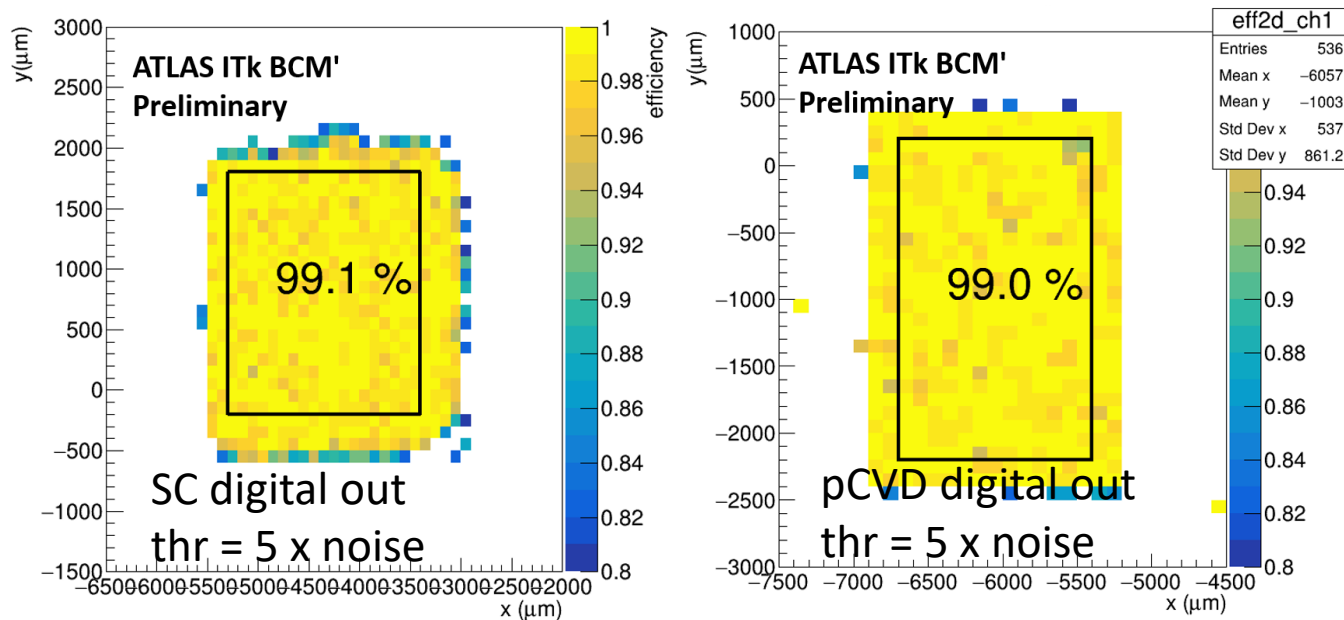
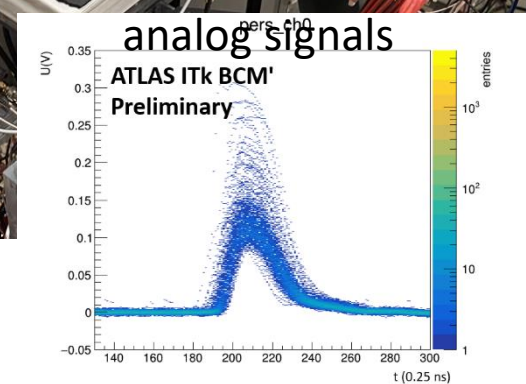
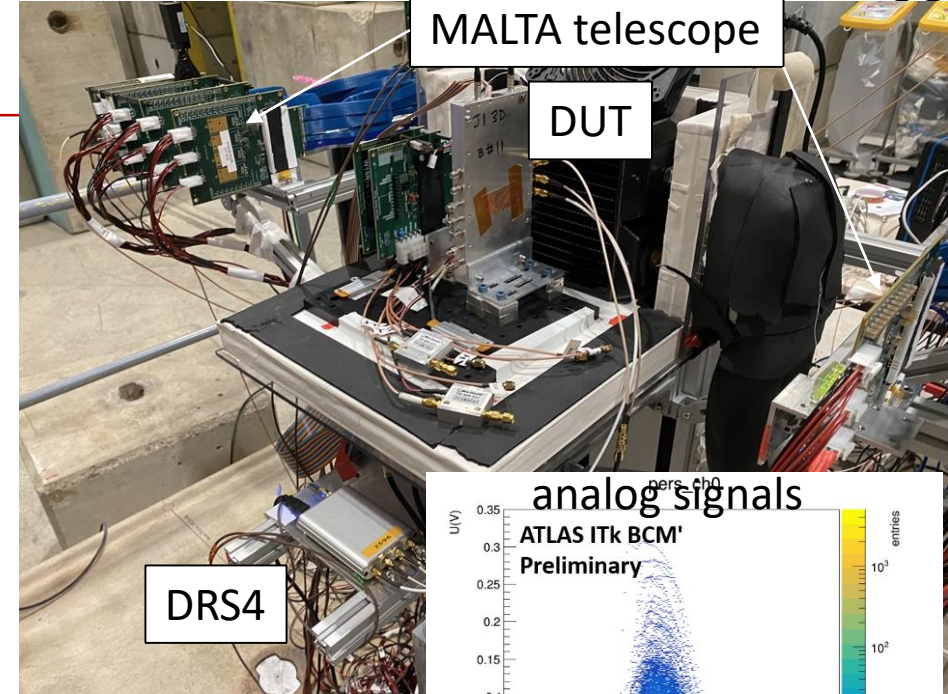
- TMR logic probably at edge of functionality

- **Not problematic for operation, since registers can be written at will**



Test beam at CERN SPS

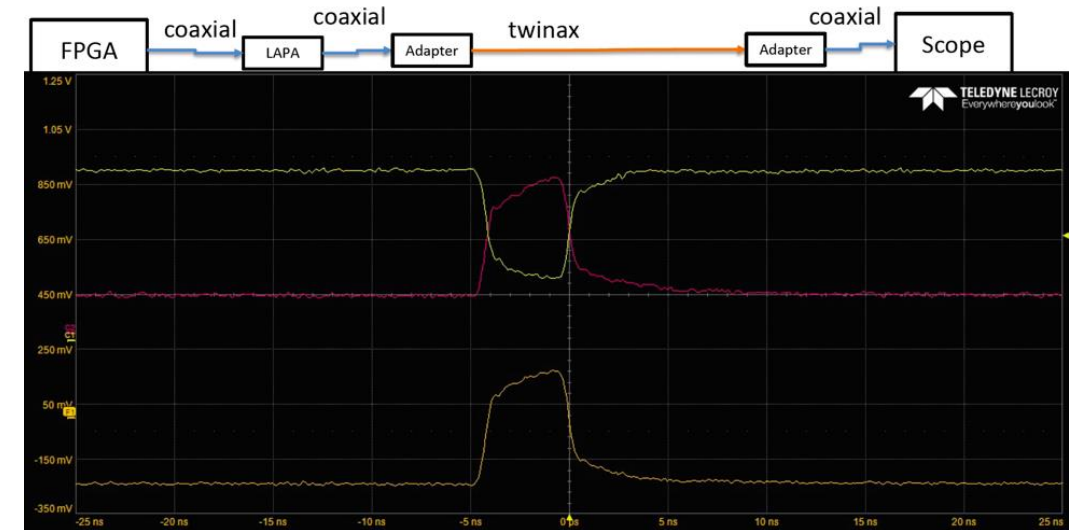
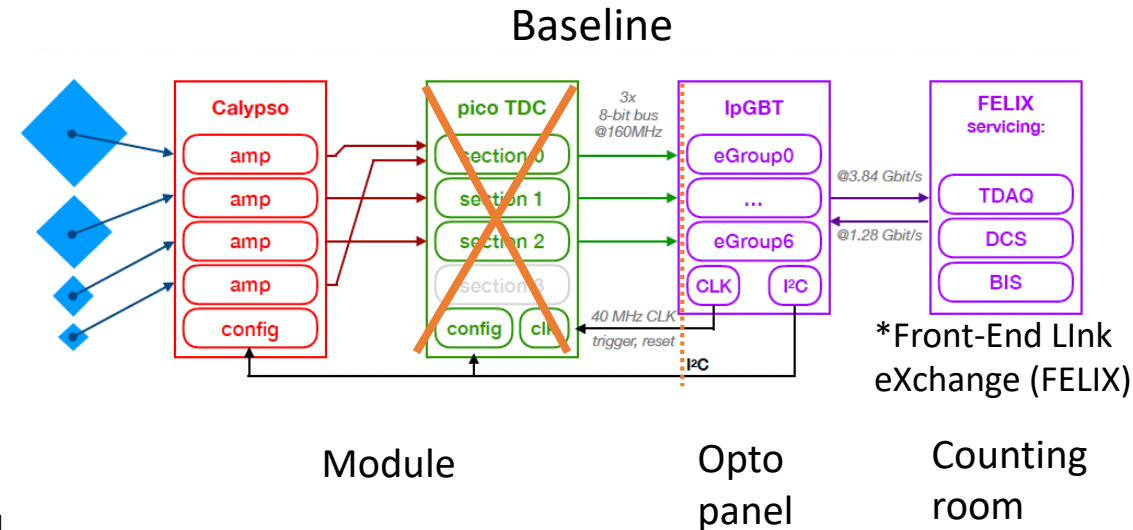
- Test beam with 120 GeV pions, MALTA CMOS telescope
- Oct and Nov 2021 with refurbished diamond sensors
- Single crystal and pCVD diamond samples (unirradiated)
- Read out analog and digital signals with DRS4 oscilloscope
- Efficiency above 99 % with digital signals in both samples
 - Analysis still ongoing



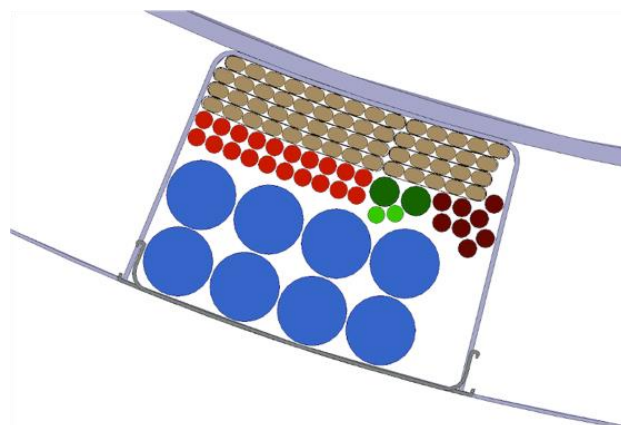
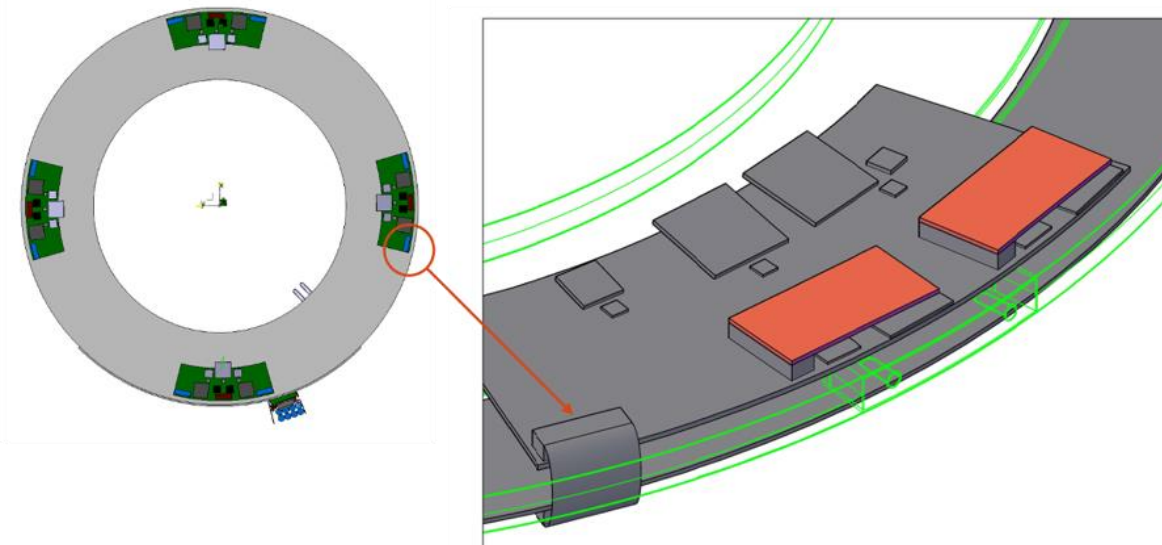
- Original baseline was

Calypso → picoTDC (digitization) → IpGBT (to optical) → FELIX*

- Use of picoTDC abandoned due to delivery, radiation issues
- IpGBT on opto-panel (lower radiation environment)
- Asynchronous electrical signals up to opto boards (5 m)
 - Twinax cable like ITk Pixel
 - LAPA asynchronous LVDS driver on station module (chip reused from MALTA CMOS pixel detector project)
 - First test over 5 m twinax done at CERN
 - Sampling rate of 1.28 GHz on IpGBT
 - To be tested
- Layout to be finalized before services freezing (early 2022)



- Four stations on dedicated R1 ring within ITk Pixel Inner System
 - Occupying 1/3 of available space on ring
- Several chips on the station
 - 3 diamond + 1 Si sensor, 3 FE (1 abort, 2 lumi), BLM, 2 LAPA, DCDC converter, DCS
- Thermal load 20 W per ring
 - Diamond sensors do not require cooling, but cooling required to mitigate radiation damage on ASIC
- Services occupy approximately 80 % of allocated service channel routing services from the rings to the tracker edges



- twinax
- HV t.p. (AWG 30)
- LV t.p. (AWG 16)
- interlock t.p. (AWG 30)
- VCAN t.p. (AWG 32)
- CAN t.p. (AWG 32)

	Name	TP/station	TP per side	Voltage	Current
HV	BLM	1	4	500V	<1uA
	3D-diamond(Lumi)	1	4	150V	<1uA
	Planar diamond (Lumi + abort)	2	8	1000V	<1uA
	Silicon	1	4	1000V	<1uA
LV	From bPOL12V	2	8	11V	3A
MOPS VCAN	Nominal 2 (but may be 4 if the capacity is available)		2 (4?)	2V	35mA
TiLock		2	8		
CAN	Nominal 2 (but may be 4 if the capacity is available)		2(4?)	50V	350mA
Twinax	Uplinks		48		
	downlinks		8		

- BCM' system will be installed in ATLAS ITk Pixel Inner system for fast beam protection and luminosity measurement
- The system includes:
 - pCVD diamond sensors
 - Fast radiation hard front end ASIC
 - LHC machine-style BLM (slow integrating)
 - IpGBT + FELIX based readout chain – baseline changed
- Different tests demonstrated functionality of the system: lab tests, SEE, test beam
- Several reviews passed, moving to preproduction/production in 2022